Quad 2-Input OR Gate

The MC10103 is a quad 2-input OR gate. The MC10103 provides one gate with OR/NOR outputs.

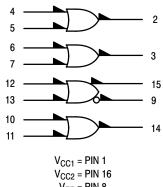
- P_D = 25 mW typ/gate (No Load)
- $t_{pd} = 2.0 \text{ ns typ}$
- t_r , $t_f = 2.0$ ns typ (20%–80%)



ON Semiconductor

http://onsemi.com

LOGIC DIAGRAM



V_{EE} = PIN 8

DIP **PIN ASSIGNMENT**

CDIP-16 **L SUFFIX CASE 620**



MARKING DIAGRAMS



PDIP-16 P SUFFIX **CASE 648**





PLCC-20 **FN SUFFIX CASE 775**



= Assembly Location

WL = Wafer Lot YY = Year WW = Work Week

$V_{CC1} \\$ 16 V_{CC2} A_{OUT} 15 COUT $\mathsf{B}_{\mathsf{OUT}}$ 3 DOUT 14 A_{IN} 13 12

 A_{IN} B_{IN} 6 11 DIN D_{IN} B_{IN} 10 V_{EE} Cout

Pin assignment is for Dual-in-Line Package. For PLCC pin assignment, see the Pin Conversion Tables on page 18 of the ON Semiconductor MECL Data Book (DL122/D).

ORDERING INFORMATION

Device	Package	Shipping		
MC10103L	CDIP-16	25 Units / Rail		
MC10103P	PDIP-16	25 Units / Rail		
MC10103FN	PLCC-20	46 Units / Rail		

ELECTRICAL CHARACTERISTICS

Characteristic Power Supply Drain Current		Pin			1	est Limits	•	l . o.	 5°C	1
Power Supply Drain Current	0	Under		1	Min		Mari		1	
	Symbol	Test 8	Min	Max 29	Min	Typ 21	Max 26	Min	Max 29	Uni mAd
Input Current	I _E	4*		390		21	245		245	-
input Current	I _{inH}	4*	0.5	390	0.5		245	0.3	245	μAd μAd
Output Voltage Logic 1		2	-1.060	-0.890	-0.960		-0.810	-0.890	-0.700	Vdα
	VOH	9	-1.060	-0.890	-0.960		-0.810	-0.890	-0.700	Vuc
Output Voltage Logic 0	V _{OL}	2 9	-1.890 -1.890	-1.675 -1.675	-1.850 -1.850		-1.650 -1.650	-1.825 -1.825	-1.615 -1.615	Vdo
Threshold Voltage Logic 1	V _{OHA}	2 9	-1.080 -1.080		-0.980 -0.980			-0.910 -0.910		Vdo
Threshold Voltage Logic 0	V _{OLA}	2 9		-1.655 -1.655			-1.630 -1.630		-1.595 -1.595	Vdc
Switching Times (50Ω Load)										ns
Propagation Delay	t ₄₊₂₊ t ₁₂₊₉ _	2 9	1.0 1.0	3.1 3.1	1.0 1.0	2.0 2.0	2.9 2.9	1.0 1.0	3.3 3.3	
Rise Time (20 to 80%)	t ₂₊	2	1.1	3.6	1.1	2.0	3.3	1.1	3.7	
Fall Time (20 to 80%)	t ₂₋	2	1.1	3.6	1.1	2.0	3.3	1.1	3.7	
OFNICE		CO								

ELECTRICAL CHARACTERISTICS (continued)

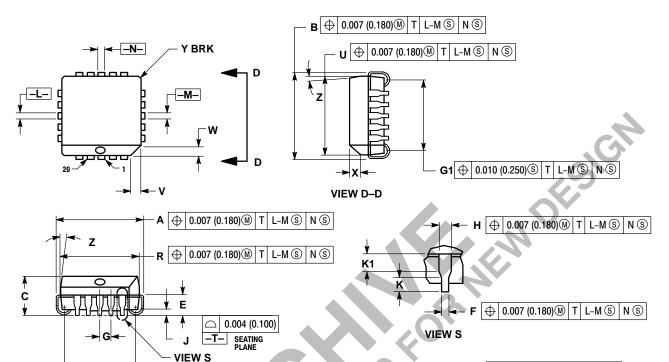
	TEST VOLTA					LTAGE VALU			
@ Test Temperature				V _{IHmax}	V _{ILmin}	V _{IHAmin}	V _{ILAmax}	V _{EE}	
–30°C				-0.890	-1.890	-1.205	-1.500	-5.2	
+25°C				-0.810	-1.850	-1.105	-1.475	-5.2	
	-0.700	-1.825	-1.035	-1.440	-5.2				
Pin			TEST V	OLTAGE AP	PLIED TO P	INS LISTED I	BELOW		
Characteri	Symbol	Under Test	V _{IHmax}	V _{ILmin}	V _{IHAmin}	V _{ILAmax}	V _{EE}	(V _{CC}) Gnd	
Power Supply Drain C	Current	ΙE	8					8	1, 16
Input Current		l _{inH}	4*	4*				8	1, 16
		I _{inL}	4*		4*			8	1, 16
Output Voltage	Logic 1	V _{OH}	2 9	4.5				8	1, 16 1, 16
Output Voltage	Logic 0	V _{OL}	2 9	12, 13				8	1, 16 1, 16
Threshold Voltage	Logic 1	V _{OHA}	2 9			4, 5	12, 13	8 8	1, 16 1, 16
Threshold Voltage	Logic 0	V _{OLA}	2 9			12, 13	4, 5	8 8	1, 16 1, 16
Switching Times	(50Ω Load)					Pulse In	Pulse Out	-3.2 V	+2.0 V
Propagation Delay		t ₄₊₂₊ t ₁₂₊₉ _	2 9			4 12	2 9	8 8	1, 16 1, 16
Rise Time	(20 to 80%)	t ₂₊	2			4	2	8	1, 16
Fall Time	(20 to 80%)	t ₂₋	2		\ \	4	2	8	1, 16

, ut under
, ied to meet the
unted on a printed c
, sistor to –2.0 volts. Test Each MECL 10,000 series circuit has been designed to meet the dc specifications shown in the test table, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 linear fpm is maintained. Outputs are terminated through a 50-ohm resistor to -2.0 volts. Test procedures are shown for only one gate. The other gates are tested in the

PACKAGE DIMENSIONS

PLCC-20 **FN SUFFIX**

PLASTIC PLCC PACKAGE CASE 775-02 ISSUE C



NOTES:

- OTES:

 1. DATUMS -L-, -M-, AND -N- DETERMINED WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.

 2. DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM -T-, SEATING PLANE.

 3. DIMENSIONS R AND U DO NOT INCLUDE MOLD FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.

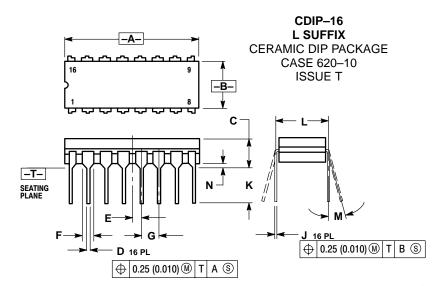
 4. DIMENSIONING AND TOLERANCING PER ANSI Y14 5M 1982
- Y14.5M, 1982. CONTROLLING DIMENSION: INCH.
- THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
- DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

	INC	HES	MILLIM	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.385	0.395	9.78	10.03
В	0.385	0.395	9.78	10.03
С	0.165	0.180	4.20	4.57
Ε	0.090	0.110	2.29	2.79
F	0.013	0.019	0.33	0.48
G	0.050	BSC	1.27	BSC
Н	0.026	0.032	0.66	0.81
J	0.020		0.51	
K	0.025		0.64	
R	0.350	0.356	8.89	9.04
U	0.350	0.356	8.89	9.04
٧	0.042	0.048	1.07	1.21
W	0.042	0.048	1.07	1.21
Χ	0.042	0.056	1.07	1.42
Υ		0.020		0.50
Z	2°	10°	2 °	10 °
G1	0.310	0.330	7.88	8.38
K1	0.040		1.02	

G1 ⊕ 0.010 (0.250)③ T L-M ⑤ N ⑤

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PACKAGE DIMENSIONS



NOTES:

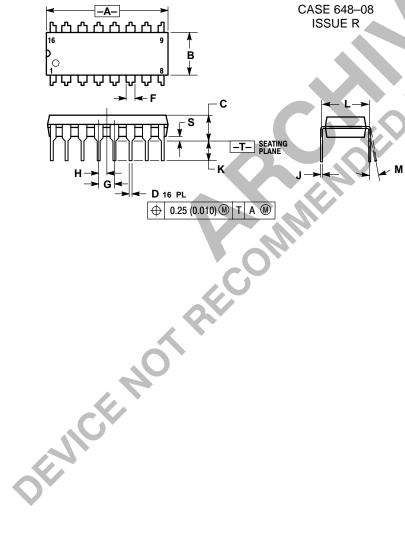
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 CONTROLLING DIMENSION: INCH.
 DIMENSION LTO CENTER OF LEAD WHEN CONTROLLING DIMENSION LTO CENTER OF LEAD WHEN

- FORMED PARALLEL

 DIMENSION F MAY NARROW TO 0.76 (0.030)
 WHERE THE LEAD ENTERS THE CERAMIC
 BODY.

	INC	HES	MILLIMETERS		
DIM	MIN MAX		MIN	MAX	
Α	0.750	0.785	19.05	19.93	
В	0.240	0.295	6.10	7.49	
C		0.200		5.08	
D	0.015	0.020	0.39	0.50	
E	0.050	BSC	1.27 BSC		
F	0.055	0.055 0.065		1.65	
G	0.100	BSC	2.54 BSC		
Н	0.008	0.015	0.21	0.38	
K	0.125	0.170	3.18	4.31	
L	0.300	BSC	7.62 BSC		
M	0 °	15°	0 °	15°	
N	0.020	0.040	0.51	1.01	





- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
 4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
 5. ROUNDED CORNERS OPTIONAL

	INC	HES	MILLIN	IETERS	
DIM	MIN MAX		MIN	MAX	
Α	0.740	0.770	18.80	19.55	
В	0.250	0.270	6.35	6.85	
С	0.145	0.175	3.69	4.44	
D	0.015	0.021	0.39	0.53	
F	0.040	0.70	1.02	1.77	
G	0.100	BSC	2.54 BSC		
Н	0.050	BSC	1.27	BSC	
J	0.008	0.015	0.21	0.38	
K	0.110	0.130	2.80	3.30	
L	0.295	0.305	7.50	7.74	
M	0°	10°	0°	10 °	
S	0.020	0.040	0.51	1.01	

Notes



Notes





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